L Number			DB	Time stamp
1	216927	<pre>(epox?\$3 near (resin\$ or novola?)) or diepox?\$3 or polyepox?\$3 or diglycidyl\$ or</pre>	USPAT;	2003/04/15 10:52
,		polyglycidyl\$	US-PGPUB; EPO; JPO; DERWENT;	
2	2605379		IBM_TDB USPAT;	2003/04/15 10:52
		circuit or wiring adj board or wiring adj substrate	US-PGPUB; EPO; JPO; DERWENT;	1000,01,10.10.32
4	382884	roughening or roughen or etch or etching	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/15 10:59
5	10519	((epox?\$3 near (resin\$ or novola?)) or diepox?\$3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$) and (semiconductor or electronic or printed adj circuit or wiring adj board or wiring adj substrate) and (roughening or roughen or etch or etching)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 10:59
6	168132	butadiene or nbr or ctbn or polybutadiene	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/15 11:02
7	1787	<pre>(((epox?\$3 near (resin\$ or novola?)) or diepox?\$3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$) and (semiconductor or electronic or printed adj circuit or wiring adj board or wiring adj substrate) and (roughening or roughen or etch or etching)) and (butadiene or nbr or ctbn or polybutadiene)</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 11:02
8	62145	oxidizing adj agent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/15 11:03
9	126	((((epox?\$3 near (resin\$ or novola?)) or diepox?\$3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$) and (semiconductor or electronic or printed adj circuit or wiring adj board or wiring adj substrate) and (roughening or roughen or etch or etching)) and (butadiene or nbr or ctbn or polybutadiene)) and (oxidizing adj agent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 11:08
10	2	"09046046"	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/15 11:09
_	216927	<pre>(epox?\$3 near (resin\$ or novola?)) or diepox?\$3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/15 10:52
_	2605379	semiconductor or electronic or printed adj circuit or wiring adj board or wiring adj substrate	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/15 10:52
-	62145	oxidizing adj agent	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/15 11:03

US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((epox?\$3 near (resin\$ or novola?)) or USPAT:	2003/04/15 08:58
EPO; JPO; DERWENT; IBM TDB 96 ((epox?\$3 near (resin\$ or novola?)) or USPAT:	
DERWENT; IBM_TDB 96 ((epox?\$3 near (resin\$ or novola?)) or USPAT:	
96 ((epox?\$3 near (resin\$ or novola?)) or USPAT:	
96 ((epox?\$3 near (resin\$ or novola?)) or USPAT:	
(tepoxity hear (resing of novola?)) or USPAT;	
dienovess or polyphovess on dialymidule and tre property	2003/04/15 08:58
diepox?\$3 or polyepox?\$3 or diglycidyl\$ or US-PGPUB; polyglycidyl\$) and (embedding adj resin) EPO; JPO;	
DERWENT;	
- 10 (oxidizing adj agent) and (((epox?\$3 near USPAT; 2	2002/04/15 02 05
(resin\$ or novola?)) or diepox?\$3 or US-PGPUB;	2003/04/15 09:05
polyepox?\$3 or diglycidyl\$ or EPO; JPO;	
polyglycidyl\$) and (embedding adj resin)) DERWENT;	
IBM TDB	
1 = 1 20705 manahanima	2003/04/15 10:52
US-PGPUB;	2003/04/15 10:52
EPO; JPO;	
DERWENT;	
IBM TDB	
7 ((epox?\$3 near (resin\$ or novola?)) or USPAT: 2	2003/04/15 09:06
diepox?\$3 or polyepox?\$3 or diglycidyl\$ or US-PGPUB.	
polyglycidyl\$) and (semiconductor or EPO: JPO:	
electronic or printed adj circuit or DERWENT:	
wiring adj board or wiring adj substrate) IBM TDB	
and (embedding adj resin) and roughening	
- 0 /ombordada	2003/04/15 09:12
US-PGPUB;	777777
EPO; JPO;	
DERWENT;	
IBM TDB	
168132 butadiene or nbr or ctbn or polybutadiene USPAT; 2	2003/04/15 11:02
US-PGPUB;	
EPO; JPO;	1
DERWENT;	
- 28579 ((epox?\$3 pear (resin\$ or novola?)) or USPAT.	
	2003/04/15 09:13
diepox?\$3 or polyepox?\$3 or diglycidyl\$ or US-PGPUB; polyglycidyl\$) and (butadiene or nbr or EPO; JPO;	
1 at bar on maladas + all	Ì
- 656 (((epox?\$3 near (resin\$ or novola?)) or USPAT; 2	2002/04/15 22 5
diamage and the moveracy of moveracy of opening	2003/04/15 09:13
dlepox?\$3 or polyepox?\$3 or diglycidyl\$ or US-PGPUB; polyglycidyl\$) and (butadiene or nbr or EPO; JPO;	
ctbn or polybutadiene)) and roughening DERWENT;	
IBM TDB	
1 ((((epox?\$3 near (resin\$ or novola?)) or $\frac{1}{1}$ 2	2003/04/15 09:13
diepox?\$3 or polyepox?\$3 or diglycidyl\$ or US-PGPUB.	.003/04/13 09:13
polyglycidyl\$) and (butadiene or nbr or EPO: JPO:	
ctbn or polybutadiene)) and roughening) DERWENT.	
and (embedding adj resin)	
$\frac{1}{2}$ $\frac{359}{(((epox?$3 near (resin$ or novola?)) or USPAT. 20$	2003/04/15 09:15
diepox?\$3 or polyepox?\$3 or diglycidyl\$ or US-PCPUB.	2, 22, 23
polyglycidyl\$) and (butadiene or nbr or EPO: JPO:	
ctbn or polybutadiene)) and roughening)	
and (semiconductor or electronic or TRM TDR	[
wiring adj substrate)	